

HITD

U11

semi conductor device with lead frame for high density mounting - has outer lead exposed

sealing resin surface

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The device includes a semi conductor chip (1) bonded with a lead frame (4). The lead frame consists of an inner lead (4a) and an outer lead (4b). The

A bonding wire (9) is used to bond the inner lead frame and the semi conductor chip. A mould resin (8) is sealed on the surface of the semi conductor chip. The main body has outer lead exposed in a sealing resin surface (8a).

ADVANTAGE - Decreases package thickness. Prevents semi conductor chip from damage. (5pp Dwg.No.2/7)

97-259719

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